

# Organizational Chart

**North America**

**Japan**

**Europe**

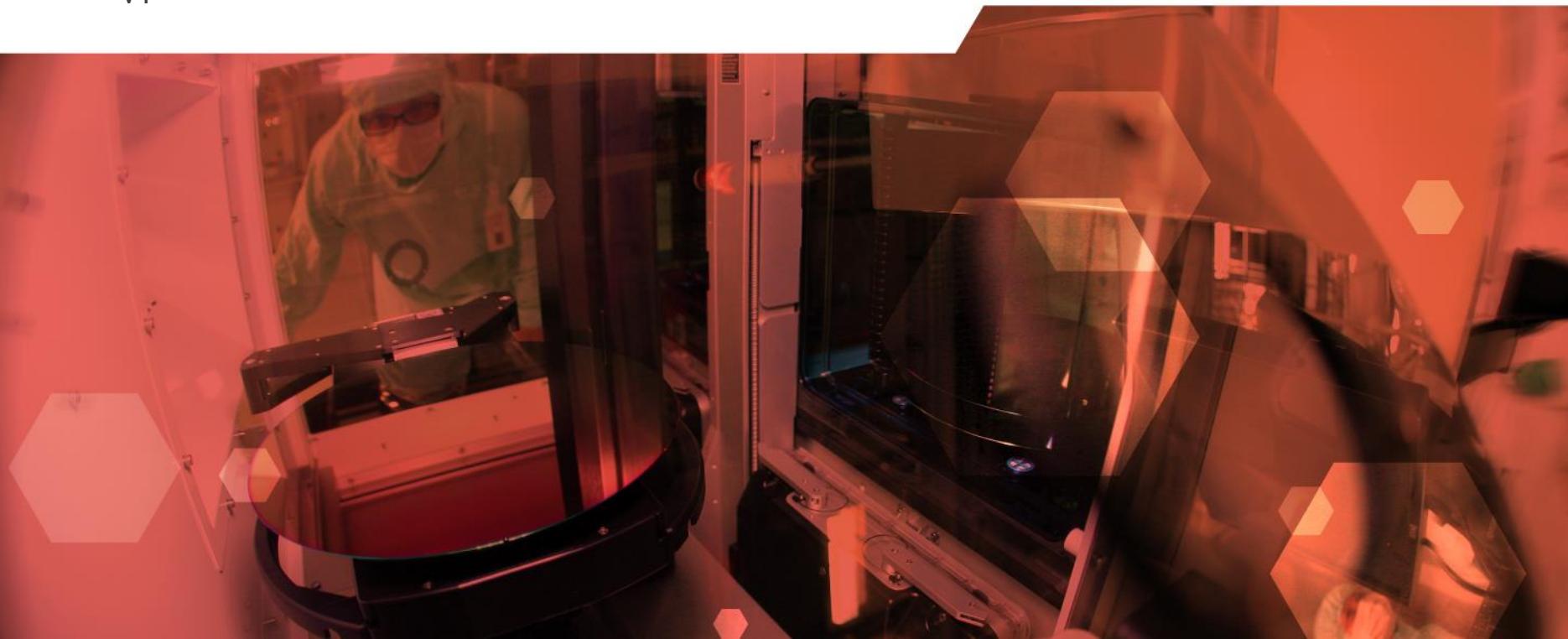
Last Updated: April 2019

v1

**Korea**

**Taiwan**

**China**



# Global Technical Committee (GTC) and Technical Committee (TC) Chapters

Global Technical Committee	<u>Locale</u>	China	Europe	Japan	Korea	<u>North</u> <u>America</u>	Taiwan
EH&S				TCC		TCC	TCC
Facilities				TCC	TCC	TCC	
Gases		TCC	TCC			TCC	
Liquid Chemicals		TCC	TCC	TCC		TCC	
FPD Materials & Components				TCC	TCC		
FPD Metrology				TCC	TCC		TCC
MEMS/NEMS						TCC	

Legend:

TCC – The Locale has a TC Chapter of the global technical committee.

CFG – The Locale has a TC Chapter Formation Group, as defined in PM 6.5, of the global technical committee.

Note 1: An underlined Locale has an RSC and may also be referred as “a Region” (e.g., “Europe Region”).

Note 2: Some TC Chapters of different global technical committees jointly hold a meeting (indicated in red rectangles).

<u>Global Technical Committee</u>	<u>Locale</u>	China	Europe	Japan	Korea	<u>North America</u>	Taiwan
Traceability				TCC		TCC	
Information & Control			TCC	TCC	TCC	TCC	TCC
Metrics			TCC	TCC		TCC	
Physical Interfaces & Carriers			TCC	TCC		TCC	
Automation Technology			TCC	TCC			TCC
Photovoltaic		TCC		TCC		TCC	TCC
PV Materials		TCC	TCC	TCC		TCC	

Legend:

TCC – The Locale has a TC Chapter of the global technical committee.

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Note 1: An underlined Locale has an RSC and may also be referred as “a Region” (e.g., “Europe Region”).

Note 2: Some TC Chapters of different global technical committees jointly hold a meeting (indicated in red rectangles).

\* In NA, Micropatterning is traditionally called Microlithography

<u>Global Technical Committee</u>	<u>Locale</u>	China	<u>Europe</u>	Japan	Korea	<u>North America</u>	Taiwan
Micropatterning (Microlithography*)						TCC	
Silicon Wafer			TCC	TCC		TCC	
Compound Semiconductor Materials			TCC	TCC		TCC	
HB-LED	TCC					TCC	
3D Packaging & Integration**				TCC		TCC	TCC
Automated Test Equipment (ATE)						TCC	

Legend:

TCC – The Locale has a TC Chapter of the global technical committee.

CFG – The Locale has a TC Chapter Formation Group, as defined in PM 6.5, of the global technical committee.

Note 1: An underlined Locale has an RSC and may also be referred as “a Region” (e.g., “Europe Region”).

\* In NA, Micropatterning is traditionally called Microlithography

\*\* 3DS-IC GTC and Assembly & Packaging GTC were integrated into one new GTC as 3D Packaging & Integration GTC in July 2017.

# Regional Standards Committee (RSC) Organizations

# SEMI Europe RSC Organization

Co-Chairs: Bert Planting – ASML, Werner Bergholz – International Standards Consulting  
Vice-Chair: Frank Petzold – Trustsec

## Europe Chapter of Automation Technology Global Technical Committee

C: Christian Hoffmann – PEER Group

## Europe Chapter of Liquid Chemicals Global Technical Committee

C: Jochen Ruth – Pall Corporation

## Europe Chapter of Physical Interfaces & Carriers Global Technical Committee

C: Alfred Honold – InReCon  
C: Frank Petzold – Trustsec

## Europe Chapter of Compound Semiconductor Materials Global Technical Committee

C: Arnd Weber – SiCrystal

## Europe Chapter of Information & Control Global Technical Committee

C: Alfred Honold – InReCon  
C: Frank Petzold – Trustsec

## Europe Chapter of PV Materials Global Technical Committee

C: Peter Wagner – Consultant  
C: Christian Hagendorf – Fraunhofer CSP

## Europe Chapter of Gases Global Technical Committee

C: Jochen Ruth – Pall Corporation

## Europe Chapter of Metrics Global Technical Committee

C: Alfred Honold – InReCon  
C: Lothar Pfitzner – FhG IISB

## Europe Chapter of Silicon Wafer Global Technical Committee

C: Werner Bergholz – International Standards Consulting  
C: Peter Wagner – Consultant  
C: Fritz Passek - Siltronic

# SEMI Japan RSC Organization

Co-Chairs: Kenji Yamagata – Daifuku, Hidetoshi Sakura – NuFlare Technology

Vice-Chair: Supika Mashiro – TEL

## Japan Chapter of 3D Packaging & Integration Global Technical Committee

C: Masahiro Tsuriya – iNEMI  
C: Haruo Shimamoto – AIST  
C: Kazunori Kato – AiT

## Japan Chapter of FPD Materials & Components Global Technical Committee

C: Tadahiro Furukawa – Yamagata University  
C: Yoshihiko Shibaura – FUJIFILM

## Japan Chapter of PV Materials Global Technical Committee

C: Takashi Ishihara – Mitsubishi Electric  
C: Kazuhiko Kashima – Consultant  
C: Tetsuo Fukuda – AIST

## Japan Chapter of Automation Technology Global Technical Committee

C: Terry Asakawa – Vistaideal Consulting  
C: Teruaki Ito – Mitsubishi Electric  
C: Fumiya Ohbuchi – SIEMENS

## Japan Chapter of FPD Metrology Global Technical Committee

C: Ryoichi Watanabe – Japan Display  
C: Akira Kawaguchi – Otsuka Electronics

## Japan Chapter of Physical Interfaces & Carriers Global Technical Committee

C: Tsuyoshi Nagashima – Miraial  
C: Kenji Yamagata – DAIFUKU  
C: Noriyoshi Toyoda – Hirata Corporation

## Japan Chapter of Compound Semiconductor Materials Global Technical Committee

C: Masayoshi Obara – Shin-Etsu Handotai

## Japan Chapter of Information & Control Global Technical Committee

C: Takayuki Nishimura – SCREEN  
Semiconductor Solutions  
C: Mitsuhiro Matsuda – KOKUSAI ELECTRIC

## Japan Chapter of Silicon Wafer Global Technical Committee

C: Naoyuki Kawai – Meiji University  
C: Tetsuya Nakai – SUMCO

## Japan Chapter of Environmental Health & Safety Global Technical Committee

C: Supika Mashiro – TEL  
C: Hidetoshi Sakura – NuFlare Technology  
C: Moray Crawford – Hatsuta Seisakusho

## Japan Chapter of Liquid Chemicals Global Technical Committee

C: Hiroshi Tomita – Toshiba Memory  
C: Hiroyuki Araki – SCREEN Semiconductor  
Solutions

## Japan Chapter of Traceability Global Technical Committee

C: Yoichi Iga – Toshiba  
C: Hirokazu Tsunobuchi – Keyence

## Japan Chapter of Facilities Global Technical Committee

C: Hiromichi Enami – Consultant  
C: Isao Suzuki – Consultant  
C: Masafumi Kitano – Fujikin

## Japan Chapter of Metrics Global Technical Committee

C: Mitsune Sakamoto – ZAMA Consulting

## Special Groups Reporting to the JRSC

## Japan Chapter of Gases Global Technical Committee

C: Hiromichi Enami – Consultant  
C: Isao Suzuki – Consultant  
C: Masafumi Kitano – Fujikin

## Japan Chapter of Photovoltaic Global Technical Committee

C: Kazuhiko Kashima – Consultant  
C: Masaaki Yamamichi – RTS Corporation

## Standardization Process Improvement (SPI)

L: Supika Mashiro – TEL

# SEMI North America (NA) RSC Organization – NA Locale

Co-Chairs: Steve Lewis – BW Design Group, Chris Evanston – Salus Engineering

Vice-Chair: Brian Rubow – Cimetrix

## NA Chapter of 3D Packaging & Integration Global Technical Committee

C: Richard Allen – NIST  
C: Sesh Ramaswami – Applied Materials  
C: Chris Moore – Covalent Metrology

## NA Chapter of HB-LED Global Technical Committee

C: Mike Feng – Silian  
C: Chris Moore – Covalent Metrology  
C: Andrew Kim – InnovationforX

## NA Chapter of Photovoltaic Global Technical Committee

C: James Moyne – AMAT/University of Michigan

## NA Chapter of Automated Test Equipment Global Technical Committee

C: Ajay Khoche – Khoche Consulting

## NA Chapter of Information & Control Global Technical Committee

C: Jack Ghiselli – Ghiselli Consulting  
C: Brian Rubow – Cimetrix  
C: James Moyne – AMAT/ University of Michigan

## NA Chapter of PV Materials Global Technical Committee

C: Hugh Gotts – Air Liquide

## NA Chapter of Compound Semiconductor Materials Global Technical Committee

C: Russ Kremer – Freiberger Compound  
Materials  
C: James Oliver – Northrop Grumman

## NA Chapter of Liquid Chemicals Global Technical Committee

C: Don Hadder – Intel  
C: Steve Rogers – KMG Chemicals  
C: Laura Ledenbach – PeroxyChem  
C: Koh Murai – Mega Fluid Systems

## NA Chapter of Physical Interfaces & Carriers Global Technical Committee

C: Matt Fuller – Entegris  
C: Melvin Jung – Intel

## NA Chapter of Environmental Health & Safety Global Technical Committee

C: Chris Evanston – Salus Engineering  
C: Sean Larsen – Lam Research  
C: Bert Planting – ASML

## NA Chapter of MEMS/NEMS Global Technical Committee

C: Steve Martell – Nordson SONOSCAN

## NA Chapter of Silicon Wafer Global Technical Committee

C: Dinesh Gupta – STA  
C: Noel Poduje – SMS  
VC: Mike Goldstein

## NA Chapter of Facilities Global Technical Committee

C: Steve Lewis – BW Design Group

## NA Chapter of Metrics Global Technical Committee

C: David Bouldin – Fab Consulting  
C: Mark Frankfurth – Cymer  
C: Vladimir Kraz – BestESD

## NA Chapter of Traceability Global Technical Committee

C: Yaw Obeng – NIST

## NA Chapter of Gases Global Technical Committee

C: Mohamed Saleem – Brooks Instrument

## NA Chapter of Microlithography Global Technical Committee

C: Bryan Barnes – NIST

## NA RSC

### Technical Architect Board

C: James Moyne – AMAT/  
University of Michigan  
C: Yaw Obeng – NIST

# SEMI North America RSC Organization – China Locale

Co-Chairs: Steve Lewis – BW Design Group, Chris Evanston – Salus Engineering

Vice-Chair: Brian Rubow – Cimetrix

China Chapter of Photovoltaic  
Global Technical Committee

C: Guangchun Zhang – CanadianSolar

China Chapter of PV Materials  
Global Technical Committee

C: Guangchun Zhang – CanadianSolar

China Chapter of HB-LED  
Global Technical Committee

C: Hongbo Zuo – AURORA

C: Jiangbo Wang – HC SemiTek

# SEMI North America RSC Organization – Korea Locale

Co-Chairs: Steve Lewis – BW Design Group, Chris Evanston – Salus Engineering

Vice-Chair: Brian Rubow – Cimetrix

Korea Chapter of Facilities  
Global Technical Committee  
C: Kwang Sun Kim – KUT

Korea Chapter of FPD Metrology  
Global Technical Committee

C: Jongho Chong – Samsung Display  
C: Kyungjin Kang – LG Electronics

Korea Chapter of FPD Materials & Components  
Global Technical Committee  
C: Jongseo Lee – Dell  
C: Il-Ho (William) Kim – Light Measurement Solution

Korea Chapter of Information & Control  
Global Technical Committee

C: Hyungsu Kim – Doople  
C: Chul Hong Ahn – SK hynix  
C: Gun Woo Lee – Lam Research

# SEMI North America RSC Organization – Taiwan Locale

Co-Chairs: Steve Lewis – BW Design Group, Chris Evanston – Salus Engineering

Vice-Chair: Brian Rubow – Cimetrix

## Taiwan Chapter of 3D Packaging & Integration

Global Technical Committee

C: Wendy Chen – King Yuan Electronics

C: Chien-Chung Lin – ITRI

C: Roger Hwang – ASE

## Taiwan Chapter of Flat Panel Display

Global Technical Committee

C: Mike Yao – CMS/ITRI

C: Jia-Ming Liu – TDMDA

## Taiwan Chapter of Automation Technology

Global Technical Committee

C: K.C. Chou – ASE

C: Jen-Hui Tsai – ITRI

C: Gwo-Sheng Peng – ITRI/CMS

C: Yung-Mao Zheng – MIRDC

## Taiwan Chapter of Information & Control

Global Technical Committee

C: Robert Chien – TSMC

## Taiwan Chapter of Environmental Health & Safety

Global Technical Committee

C: Shuh-Woei Yu – SAHTECH

## Taiwan Chapter of Photovoltaic

Global Technical Committee

C: T.C. Wu – CMS/ITRI

C: J.S. Chen – TeraSolar

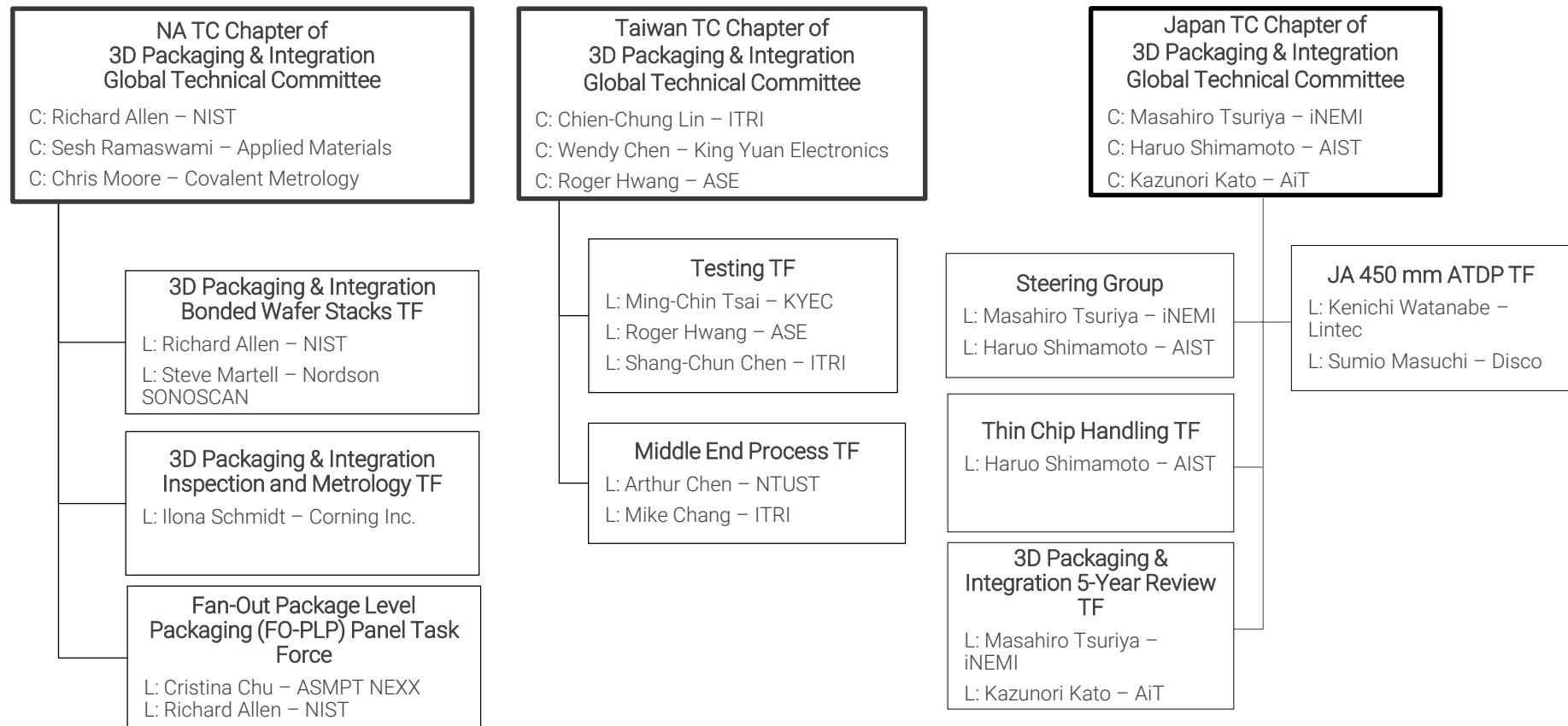
C: Ray Sung – UL Taiwan

## ISC Taiwan Advisor

Tzeng-Yow Lin – CMS/ITRI

# Organization of Each TC Chapter

# 3D Packaging & Integration (3DP&I) Global Technical Committee

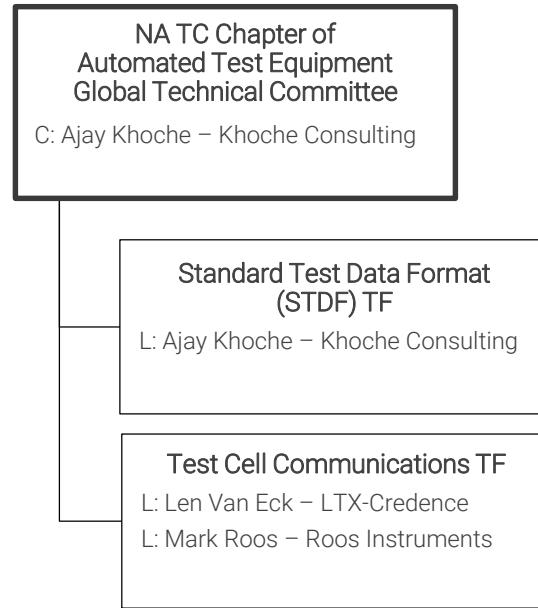


# Automation Technology (AT) Global Technical Committee

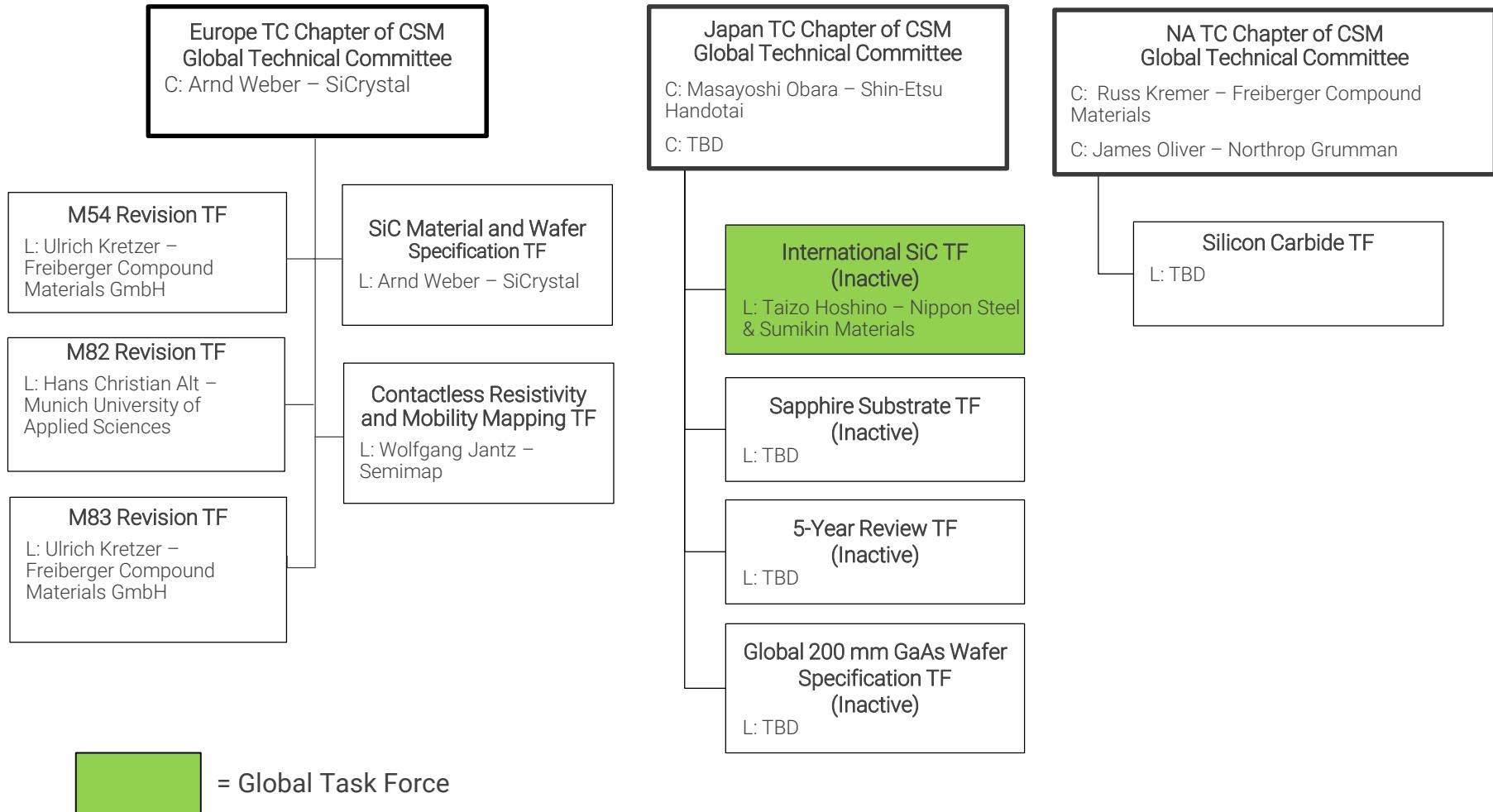


= Global Task Force

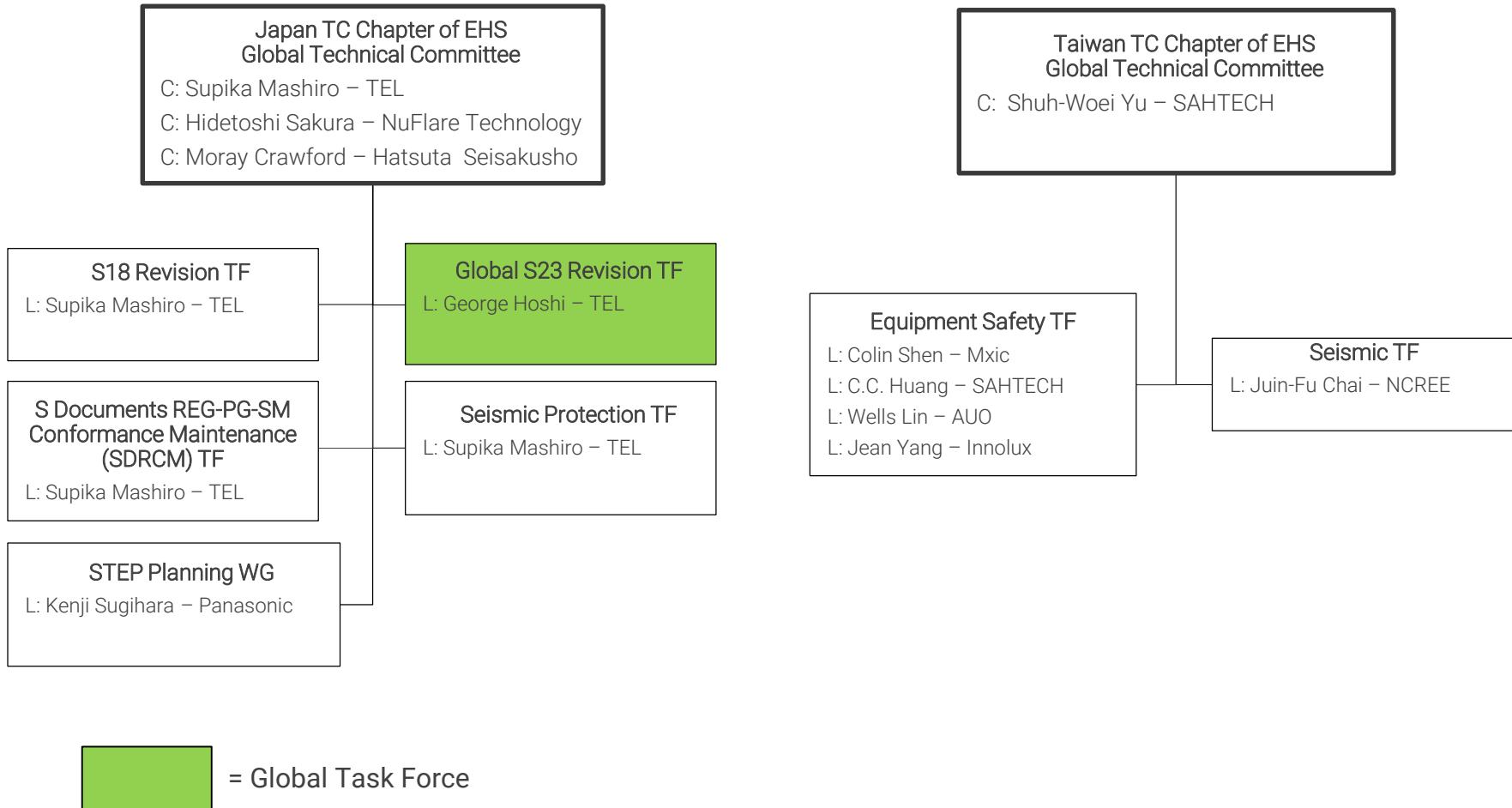
# Automated Test Equipment (ATE) Global Technical Committee



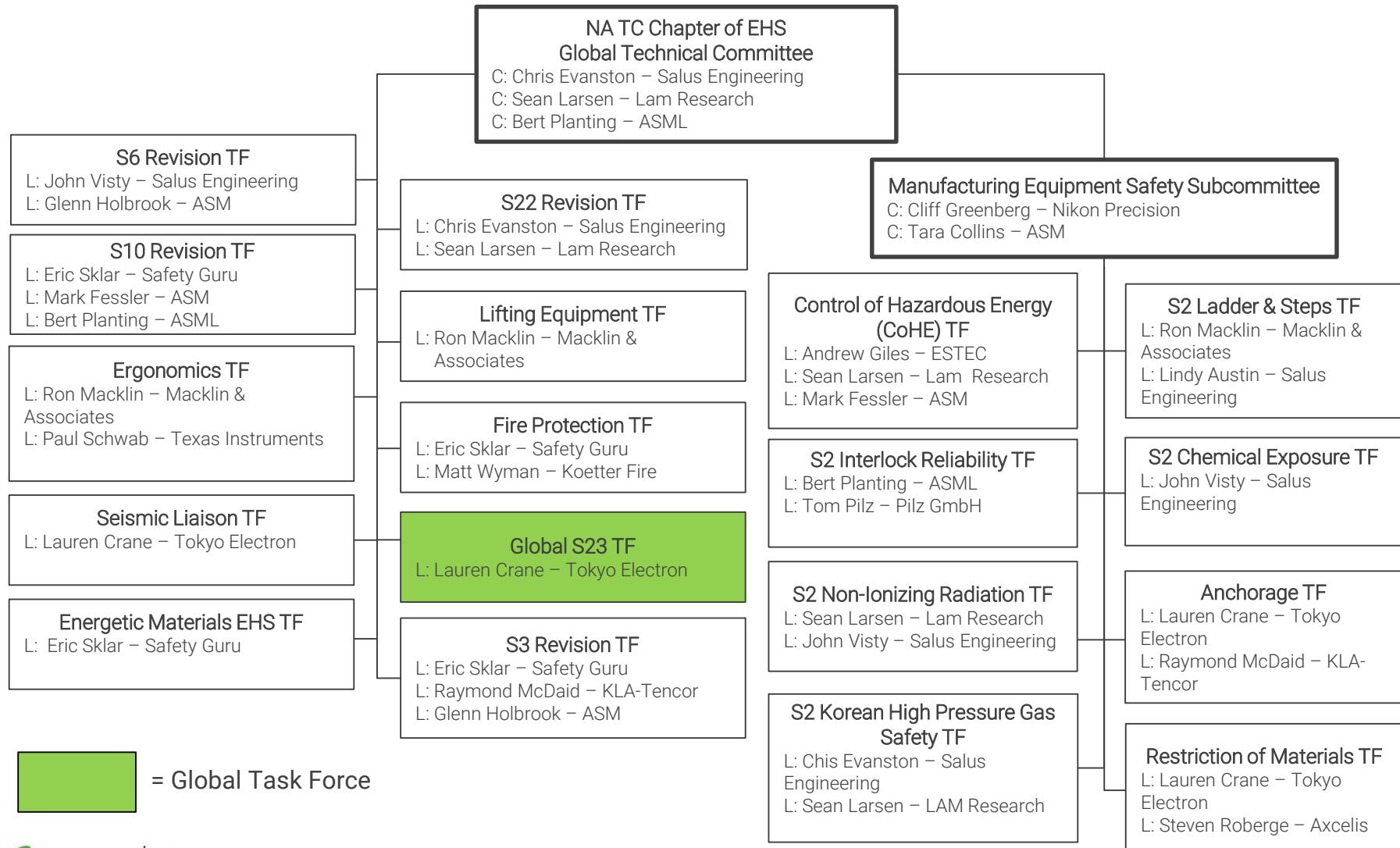
# Compound Semiconductor Materials (CSM) Global Technical Committee



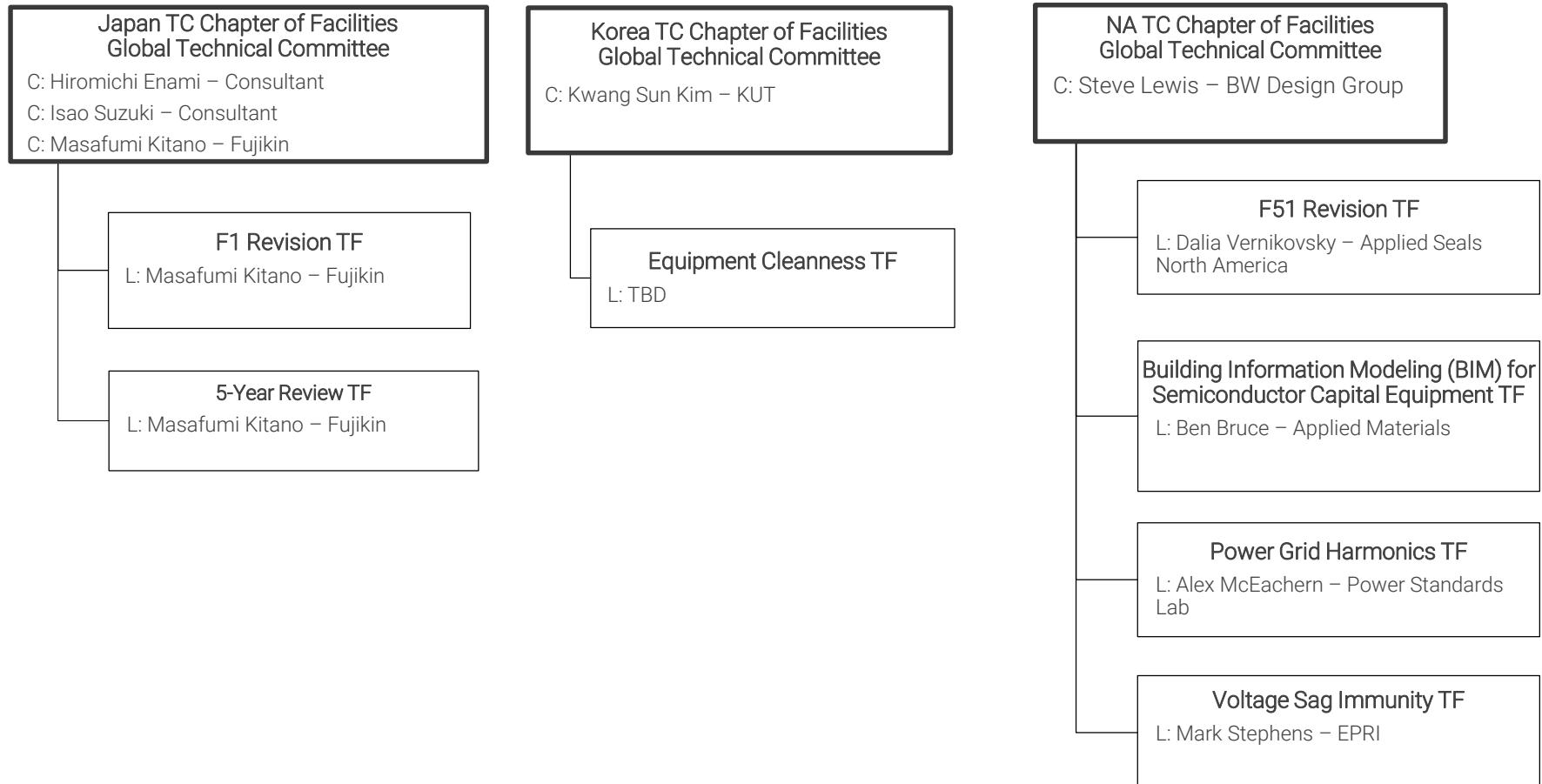
# Environmental, Health & Safety (EH&S) Global Technical Committee



# **Environmental, Health & Safety (EH&S) Global Technical Committee**



# Facilities Global Technical Committee



# FPD Metrology Global Technical Committee

## Japan TC Chapter of FPD Metrology Global Technical Committee

C: Ryoichi Watanabe – Japan Display  
C: Akira Kawaguchi – Otsuka Electronics

## Korea TC Chapter of FPD Metrology Global Technical Committee

C: Jongho Chong – Samsung Display  
C: Kyungjin Kang – LG Electronics

## Taiwan TC Chapter of FPD Metrology Global Technical Committee

C: Mike Yao – CMS/ITRI  
C: Jia-Ming Liu – TDMDA

### Perceptual Viewing Angle TF

L: Myongyoung Lee – LG Electronics

### Perceptual Image Quality TF

L: Jongho Chong – Samsung  
Display

### Flexible Display TF

L: Chao-Hua Wen – ITRI

### Transparent Display TF

L: Pei-Li Sun – NTUST  
L: Justic Lin – Acer

# FPD Materials & Components Global Technical Committee

Japan TC Chapter of FPD Materials & Components  
Global Technical Committee

C: Tadahiro Furukawa – Yamagata University  
C: Yoshihiko Shibahara – Fujifilm

Flexible Display TF

L: Haruhiko Itoh – Teijin  
L: Tadahiro Furukawa – Yamagata University

FPD Color Filter TF

L: Tadahiro Furukawa – Yamagata University

FPD Mask TF

L: Kazuya Shiojiri – SK Electronics  
L: Hirofumi Ihara – HOYA

Polarizing Film TF

L: Yoshihiko Shibahara – Fujifilm  
L: Motoshige Tatsumi – Nitto Denko

Korea TC Chapter of FPD Materials & Components  
Global Technical Committee

C: Jongseo Lee – Dell  
C: Il-Ho (William) Kim – Light Measurement Solution

# Gases

## Global Technical Committee

Europe TC Chapter of Gases  
Global Technical Committee

C: Jochen Ruth – Pall Corporation

Japan TC Chapter of Gases  
Global Technical Committee

C: Hiromichi Enami – Consultant  
C: Isao Suzuki – Consultant  
C: Masafumi Kitano – Fujikin

NA TC Chapter of Gases  
Global Technical Committee

C: Mohamed Saleem – Brooks  
Instrument

Permeation Tubes for Trace  
Moisture Calibration TF

L: Jean-Marie Collard – Solvay  
Chemicals  
L: Jim McKinley – KIN-TEK

Cleaning Gases TF

L: Jean-Marie Collard – Solvay  
Chemicals

Filters & Purifiers TF

L: Mohamed Saleem – Brooks  
Instrument  
L: Yanli Chen – UCT

Heater Jacket TF

L: Matt Milburn – UCT  
L: David Colquhoun –  
BriskHeat

Mass Flow Controller TF

L: Mohamed Saleem –  
Brooks Instrument  
L: Erica Kitano – Fujikin

Gases Specification TF

L: Mohamed Saleem –  
Brooks Instrument  
L: Thomas Fritz – WIKA

Materials of Construction Gas  
Delivery Systems TF

L: Bill Kiikvee – AP Tech

Pressure Measurement TF  
(Inactive)

L: Yanli Chen – UCT  
L: Jeff Christian – WIKA

Surface Mount Sandwich  
Component Dimensions TF  
(Inactive)

L: Matt Milburn – UCT

# HB-LED Global Technical Committee

## China TC Chapter of HB-LED Global Technical Committee

C: Hongbo Zuo – AURORA  
C: Jiangbo Wang – HC SemiTek

### Single Crystal Sapphire TF

L: Yong Ji – Guizhou Haotian Optoelectronics Technology  
L: Xinhong Yang – AURORA

### Sapphire Single Crystal Ingot TF

L: Hongbo Zuo – AURORA

### GaN based LED Epitaxial Wafer TF

L: Jiangbo Wang – HC SemiTek

### Sapphire Single Crystal Orientation TF (Inactive)

L: Songbin Zhao – DDXDF

### Patterned Sapphire Substrate TF

L: Jianzhe Liu – ECBO

### HB-LED Equipment Communication Interface TF

L: Steven Lee – AMEC  
L: Clare Liu – Cimetrix

## NA TC Chapter of HB-LED Global Technical Committee

C: Mike Feng – Silian  
C: Chris Moore – Covalent Metrology  
C: Andrew Kim – InnovationforX

### Patterned Sapphire Substrate (PSS) TF

L: Open

### HB-LED Equipment Communication Interfaces TF (Inactive)

L: Brian Rubow – Cimetrix

### HB-LED Equipment Automation Interfaces TF (Inactive)

L: Daniel Babbs – Brooks Automation  
L: Jeff Felipe – Entegris

### Test Methods TF (Inactive)

L: Peter Wagner – Self

### HB-LED Wafer TF

L: Open

### HB-LED Impurities & Defects in Sapphire Wafers TF (Inactive)

L: Luke Glinski – GT Advanced Technologies

### HB-LED Source Materials TF (Korea)

L: Paul Ahn – Veeco  
L: H.B. Joo – Aixtron  
L: Sungjin Jun – LG Innotek  
L: Deok-gil – Samsung Electronics

# Information & Control (I&C) Global Technical Committee

## Europe TC Chapter of Information & Control Global Technical Committee

C: Alfred Honold – InReCon  
C: Frank Petzold – Trustsec

### Process Control Systems TF

L: Martin Schellenberger – FhG  
IISB

## Japan TC Chapter of Information & Control Global Technical Committee

C: Takayuki Nishimura – SCREEN Semiconductor Solutions  
C: Mitsuhiro Matsuda – KOKUSAI ELECTRIC  
TA: Tadashi Mochizuki – TEL  
Adviser: Mitch Sakamoto – Zama Consulting

### GEM300 TF

L: Yuko Toyoshima – Hitachi High Technologies  
L: Masaya Nagata – TEL

### Japan I&CC Maintenance TF

L: Mitsuhiro Matsuda – KOKUSAI ELECTRIC

### Sensor Bus TF

L: Hideaki Ogihara – NaigaiTEC  
L: Tadashi Somei – Pionics  
L: Hajime Miura – Techno-Holon

### Backend Factory Integration TF

L: Hideaki Ogihara – Naigai TEC

## Korea TC Chapter of Information & Control Global Technical Committee

C: Hyungsu Kim – Doople  
C: Chul Hong Ahn – SK hynix  
C: Gun Woo Lee – Lam Research

### GEM300 TF

L: Jong Sub Shim – ASM  
L: Chang Yul Cho – SEMES  
L: Byoung Min Im – TEL Korea

### Diagnostic Data Acquisition (DDA) TF

L: Hyungsu Kim – Doople  
L: Inhyeok Paek – Linkgenesis

### Advanced Back-End Factory Integration (ABFI) TF

L: Y.S. Lim – Miracom Inc.

### Equipment Data Acquisition (EDA) WG

L: Mitch Sakamoto – ZAMA Consulting  
L: Takashi Nakagawa – Yokogawa Solution Service

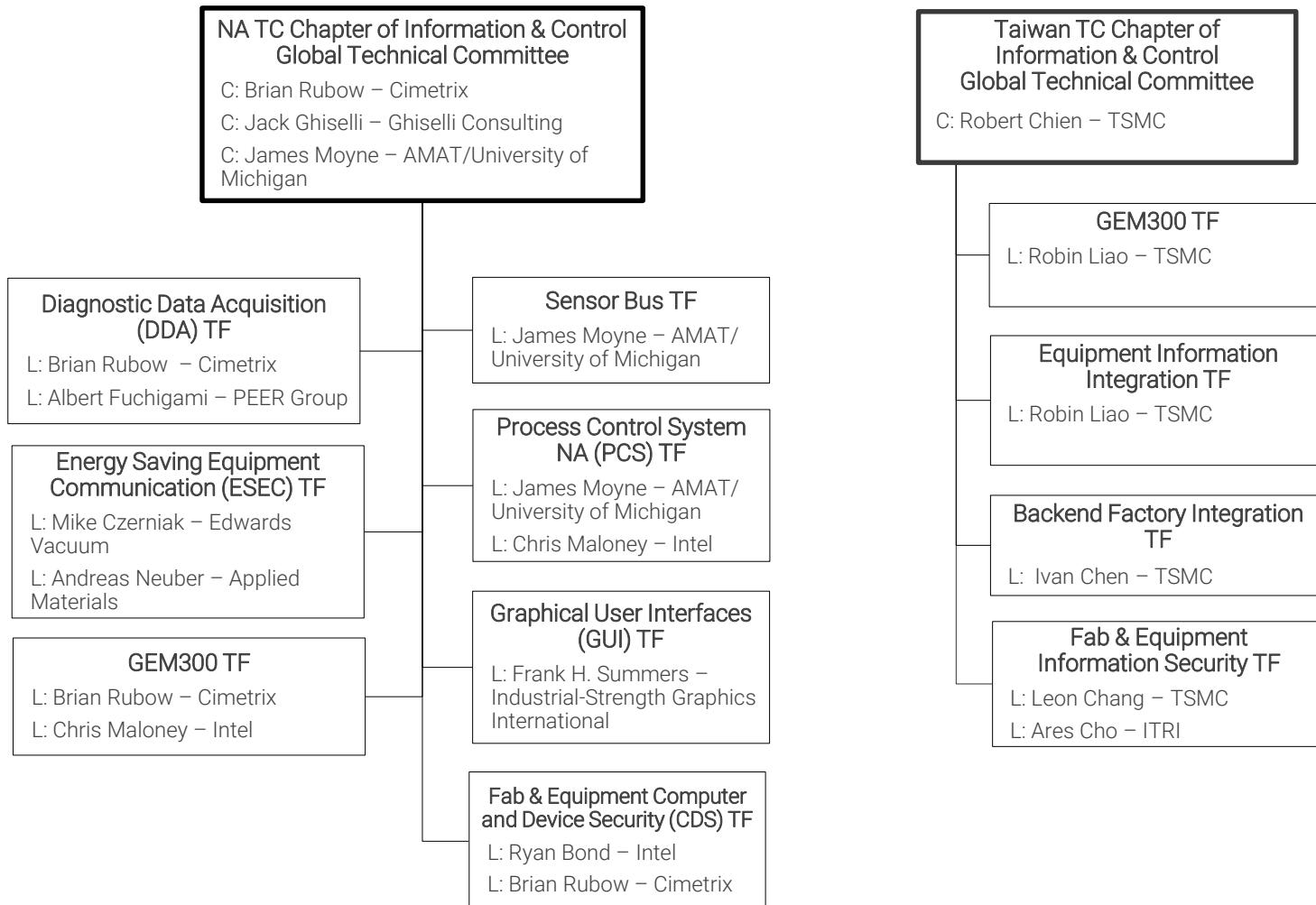
### Diagnostic Data Acquisition (DDA) TF

L: Mitch Sakamoto – ZAMA Consulting  
L: Takashi Nakagawa – Yokogawa Solution Service

### Fab & Equipment Information Security TF

L: Tadashi Mochizuki – Tokyo Electron

# Information & Control (I&C) Global Technical Committee



# Liquid Chemicals Global Technical Committee

## Europe TC Chapter of Liquid Chemicals Global Technical Committee

C: Jochen Ruth – Pall Corporation

Precursor Specifications TF  
L: Paul Williams – SAFC Hitech

Solvents in Advanced  
Processes TF  
L: TBD

## Japan TC Chapter of Liquid Chemicals Global Technical Committee

C: Hiroshi Tomita – Toshiba Memory  
C: Hiroyuki Araki – SCREEN  
Semiconductor Solutions

### Liquid Filter TF

L: Takuya Nagafuchi – Nihon  
Entegris  
L: Takehito Mizuno – Nihon Pall

### Liquid-Borne Particle Counter TF

L: Kaoru Kondo – RION  
L: Kazutoshi Kato – PMS  
Division/Spectris Co., Ltd.

### Diaphragm Valve TF

L: Shigeru Ohsugi – CKD  
L: Kimihito Sasao – Advance  
Electric

### Welding Fitting TF

L: Kimihito Sasao – Advance  
Electric  
L: Takashi Hasegawa – KITZ SCT

### Ultrapure Liquid Evaluation Study Group

L: Kaoru Kondo – RION  
L: Hiroshi Sugawara – ORGANO

## NA TC Chapter of Liquid Chemicals Global Technical Committee

C: Don Hadder – Intel  
C: Steve Rogers – KMG Chemicals  
C: Laura Ledenbach – PeroxyChem  
C: Koh Murai – Mega Fluid Systems

### Chemical Analytical Methods (CAM) TF

L: Don Hadder – Intel  
L: David Kandiyeli – Mega Fluid  
Systems

### High Purity Liquid Assemblies & Systems TF (Inactive)

L: Koh Murai – Mega Fluid  
Systems  
L: David Kandiyeli – Mega  
Fluid Systems

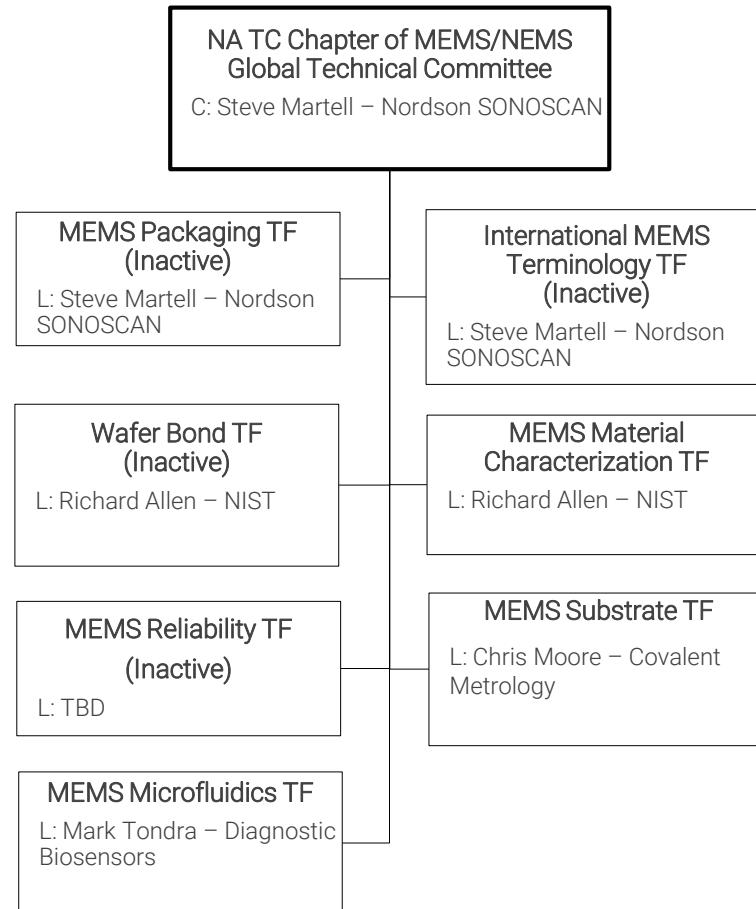
### High Purity Polymer Materials & Components TF

L: Bob McIntosh – GF Piping

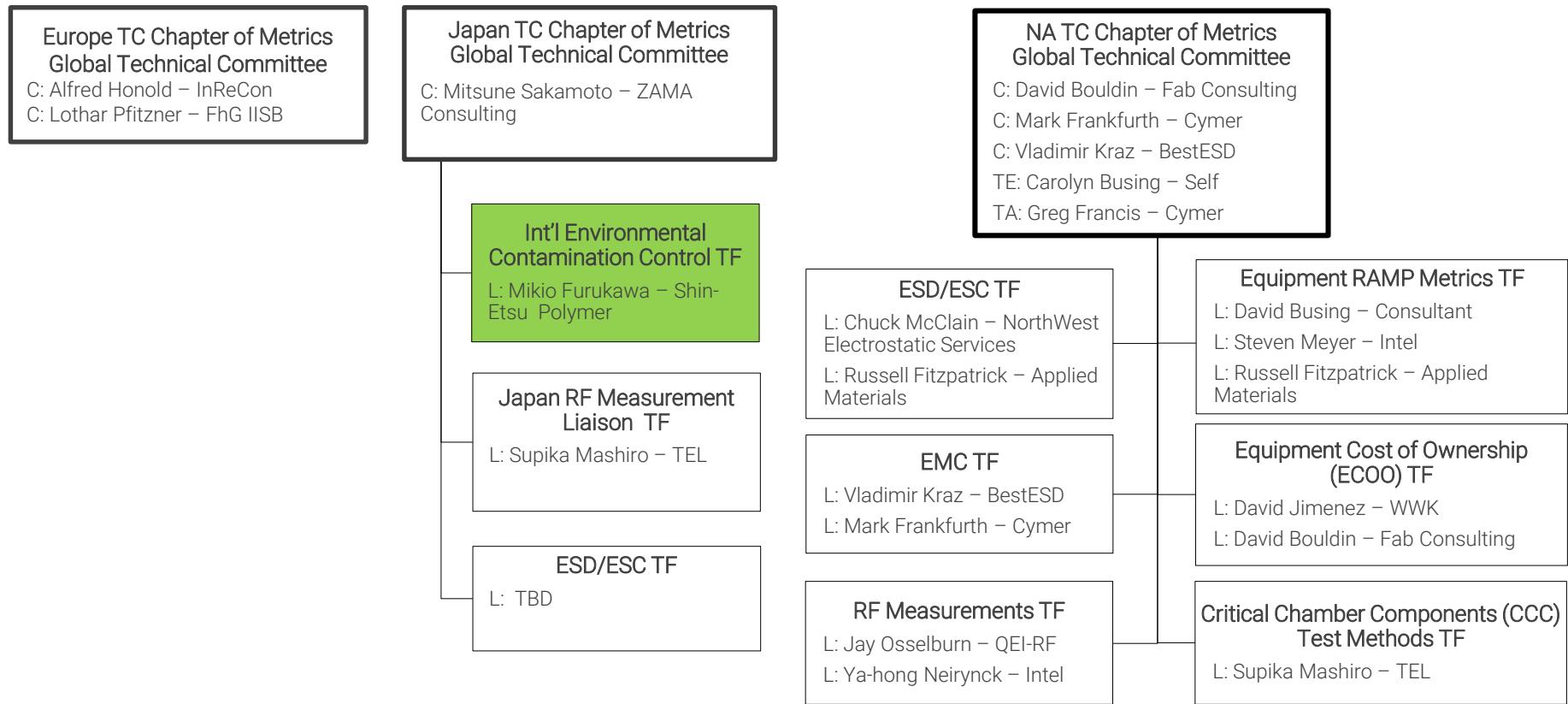
### Ultra Pure Water (UPW) TF

L: Slava Libman – FTD Solutions  
L: Bob McIntosh – GF Piping

# MEMS/NEMS Global Technical Committee

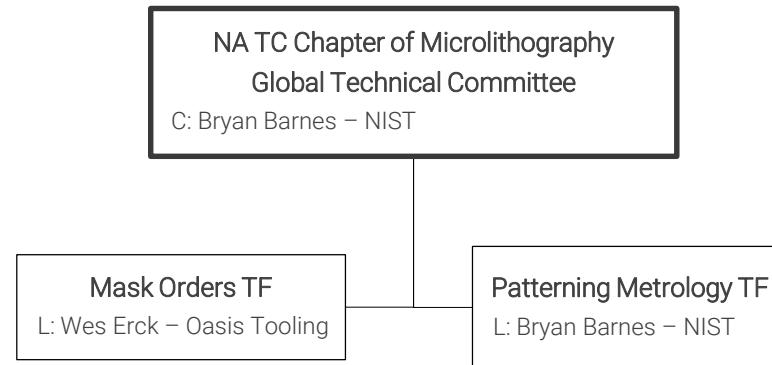


# Metrics Global Technical Committee



= Global Task Force

# Micropatterning Global Technical Committee



# Photovoltaic (PV) Global Technical Committee

## China TC Chapter of PV Global Technical Committee

C: Guangchun Zhang – CanadianSolar

## Japan TC Chapter of Photovoltaic Global Technical Committee

C: Kazuhiko Kashima – Consultant  
C: Masaaki Yamamichi – RTS Corporation

## Taiwan TC Chapter of PV Global Technical Committee

C: T.C. Wu – CMS/ITRI  
C: J.S. Chen – TeraSolar  
C: Ray Sung – UL Taiwan

### Crystalline Silicon Solar Cell TF

L: Dengyuan Song – Yingli Energy  
L: Rulong Chen – Suntech  
L: Xianwu Cai – CETC-48<sup>th</sup>

### PV Diffusion Furnace Test Methods TF

L: Zhou Hongbiao – CETC-48<sup>th</sup>  
L: Cai Xianwu – Red Solar  
L: Li Buzhong – NAURA  
L: Zheng Jianyu – NAURA

### PV Module TF

L: Wei Zhou – Trina Solar  
L: Liang Luo – Hunan Red Solar  
L: Zhen Zhang – Hohai University  
L: Jingbing Zhu – SUNMAN

### Testing Equipment TF

L: Hui Long – CETC-48<sup>th</sup>  
L: Zhiqiang Ding – Trina Solar

### Thin Film PV Module TF

L: Yaohua Mai – Jinan University  
L: Xinwei Niu – JA Solar  
L: Jian Ding – Hanergy

### Multi-Wire Saws TF

L: Jingying Jia – NERCPVE  
L: Xianwu Cai – CETC-48<sup>th</sup>  
L: Zhixin Li – LCT  
L: Wenli Lv – CETC-48<sup>th</sup>

### Building Integrated Photovoltaic (BIPV) TF

L: Dengyuan Song – Yingli Energy  
L: Jingbin Zhu – SUNMAN  
L: Jian Ding – Hanergy  
L: Pengjun Xiao – CTC

### PV Package Performance TF

L: C.C. Lin – PV Guider  
L: T.C. Wu – CMS/ITRI  
L: K.T. Lee – King Design

### PV Reliability Test Method TF

L: H.S. Wu – CMS/ITRI

### Organic and Dye Sensitized Solar Cell & Perovskite Solar Cell TF

L: D. R. Huang – NDHU  
L: T.C. Wu – CMS/ITRI  
L: Kevin Chou – EVERLIGHT

# PV Materials Global Technical Committee

China TC Chapter of PV Materials  
Global Technical Committee

C: Guangchun Zhang – CanadianSolar

PV Silicon Raw Materials TF

L: Lu Wenfeng – GCL  
L: Dongxu Chu – SINOSICO  
L: Li He – CPVT

PV Silicon Wafer TF

L: Yuepeng Wan – GCL  
L: Liangping Deng – LONGi  
L: Jingang Lu – HI-TECH

Europe TC Chapter of PV Materials  
Global Technical Committee

C: Peter Wagner – Consultant  
C: Christian Hagendorf – FhG-CSP

Int'l PV Analytical Test  
Methods, Metrology, and  
Inspection TF

L: TBD

PV Silicon Materials TF

L: Peter Wagner –  
Consultant

PV Material Degradation  
TF

L: Max Koentopp –  
Hanwha Q-cells  
L: Christian Hagendorf –  
FhG-CSP

Japan TC Chapter of PV Materials  
Global Technical Committee

C: Takashi Ishihara – Mitsubishi  
Electric  
C: Kazuhiko Kashima – Consultant  
C: Tetsuo Fukuda – Nihon University

Japan PV Materials TF

L: Tetsuo Fukuda – Nihon  
University  
L: Takashi Ishihara –  
Mitsubishi Electric

NA TC Chapter of PV Materials  
Global Technical Committee

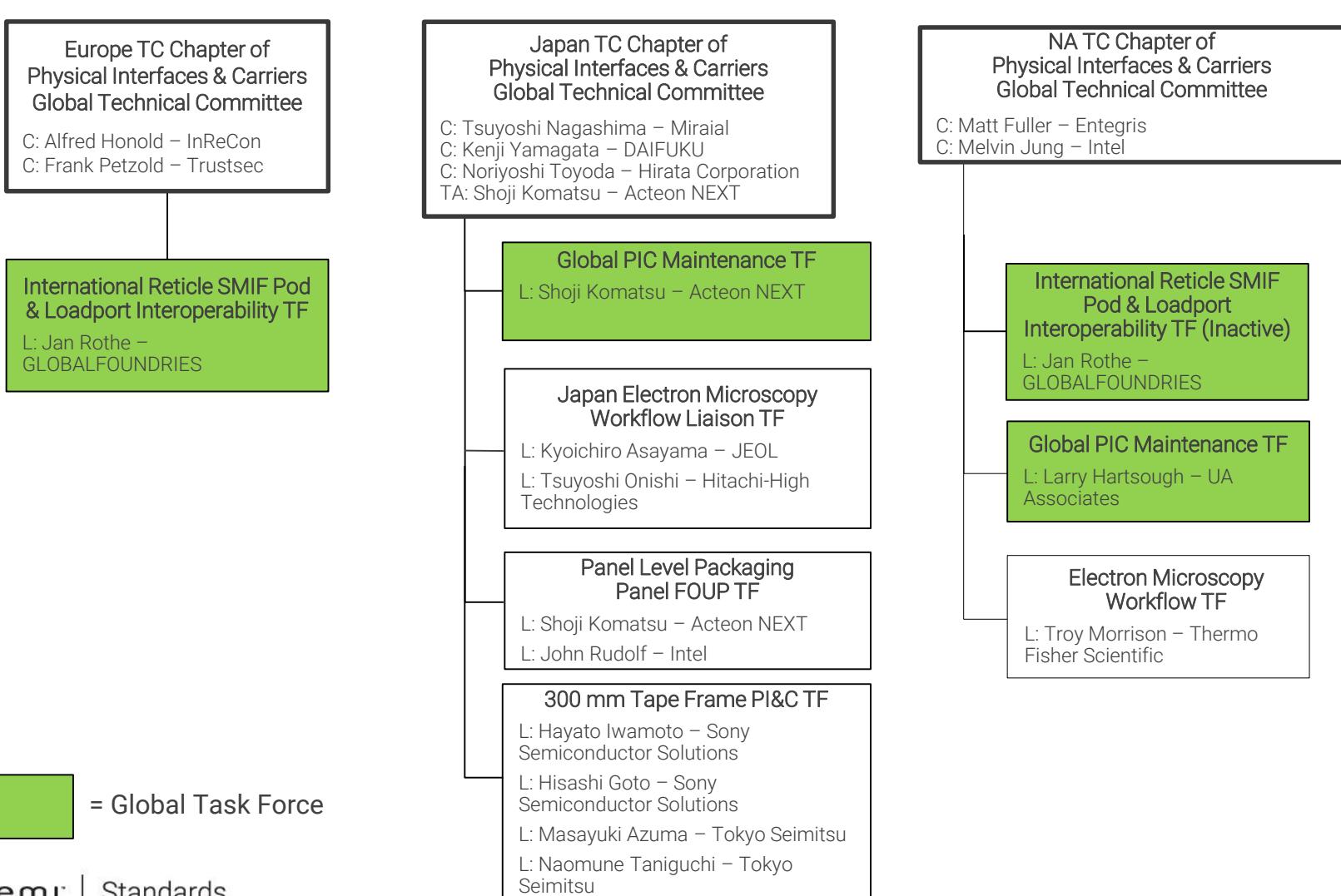
C: Hugh Gotts – Air Liquide  
Electronics US

Int'l PV Analytical Test  
Methods, Metrology, and  
Inspection TF

L: Hugh Gotts – Air Liquide  
Electronics US  
L: Chris Moore – Covalent  
Metrology

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# Physical Interfaces & Carriers (PIC) Global Technical Committee



# Silicon Wafer Global Technical Committee

## Europe TC Chapter of Silicon Wafer Global Technical Committee

C: Werner Bergholz – Jacobs University of Bremen  
C: Peter Wagner – Consultant  
C: Fritz Passek – Siltronic

### International Advanced Surface Inspection TF

L: Frank Riedel – Siltronic

### International Advanced Wafer Geometry TF

L: Fritz Passek – Siltronic  
L: Frank Riedel – Siltronic

### International Terminology TF

L: Peter Wagner – Consultant

### International Test Methods TF

L: Peter Wagner – Consultant

### International Polished Wafers TF

L: Frank Riedel – Siltronic

## NA TC Chapter of Silicon Wafer Global Technical Committee

C: Dinesh Gupta – STA  
C: Noel Poduje – SMS

### International Annealed Wafers TF

L: Dinesh Gupta – STA

### International Terminology TF

L: TBD

### International Epitaxial Wafers TF

L: Dinesh Gupta – STA

### International Test Methods TF

L: Dinesh Gupta – STA

### International Polished Wafers TF

L: John Valley – Nanometrics

### International Advanced Wafer Geometry TF

L: Noel Poduje – SMS

### International SOI Wafers TF

L: Gerd Pfeifter – GLOBALFOUNDRIES

### International Automated Advance Surface Inspection TF

L: Kurt Haller – KLA-Tencor

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# Silicon Wafer Global Technical Committee

International Terminology TF  
L: Tetsuya Nakai – SUMCO

International SOI Wafers TF  
L: Atsushi Ogura – Meiji University  
L: Tetsuya Nakai – SUMCO

International Polished Wafers TF  
L: Yasutoshi Takamoti – GlobalWafers Japan

International Annealed Wafers TF  
L: Koji Araki – GlobalWafers Japan

International Epitaxial Wafers TF  
L: Naohisa Toda – Shin-Etsu Handotai

Japan TC Chapter of Silicon Wafer Global Technical Committee

C: Naoyuki Kawai – Meiji University  
C: Tetsuya Nakai – SUMCO

International Test Method TF  
L: Ryuji Takeda – GlobalWafers Japan

Japan Test Method TF  
L: Ryuji Takeda – GlobalWafers Japan  
L: Tsuyoshi Otsuki – Shin-Etsu Handotai  
L: Mikako Omata – SCAS

Surface Metal Chemical Analysis WG  
L: Ryuji Takeda – GlobalWafers Japan  
L: Ryo Machida – SCAS

Bulk Heavy Metal Analysis by Electrical Measurement WG  
L: Shingo Sumie – KOBELCO  
L: Masaru Akamatsu – KOBELCO

GOI WG  
L: Tsuyoshi Otsuki – Shin-Etsu Handotai

Surface Organic Contaminant Analysis WG  
L: Mikako Omata – SCAS

BMD DZ WG  
L: Ryuji Takeda – GlobalWafers Japan

JA Shipping Box

L: Shoji Komatsu – Acteon NEXT  
L: Tsuyoshi Nagashima – Miraial

International 450 mm Shipping Box TF

L: Shoji Komatsu – Acteon NEXT

International Advanced Wafer Geometry TF

L: Satoshi Akiyama – Raytex Optima

Japan JWG TF

L: Masanori Yoshise – Wafer Information Service  
L: Satoshi Akiyama – Raytex Optima

International Advanced Surface Inspection TF

L: Masami Ikota – Hitachi-High Technologies

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# Traceability Global Technical Committee

